12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# # 20250625003.0
Qualify New Assembly Material set for Selected Device(s)
Information Only

Date: June 26, 2025
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20250625003.0
Information Only
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	**CUSTOMER PART NUMBER**
F280039CSPZR	NULL
F280039SPM	NULL
F280037SPZ	NULL
F280039CSPM	NULL
F280037CSPZ	NULL
F280039CSPZ	NULL
F280033SPM	NULL
F280034SPZ	NULL
F280039CSPMR	NULL
F280033SPZ	NULL
F280039SPZ	NULL

Technical details of this Product Change follow on the next page(s).

Notification Number:	20250625003.0	**Notification Date:**	June 26, 2025
Title:	Qualify New Assembly Material set for Selected Device(s)		
Customer Contact:	Change Management team	**Dept:**	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Materials
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments is pleased to announce the qualification of new assembly material for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

Material	Current	Proposed
Mold compound (PM, PZ)	4212581	4211649

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Total FIT will remain below SIL Target.

Package	Total FIT	SIL2 Target
PM	107.1	≤1000
PZ	107.64	≤1000

Changes to product identification resulting from this notification:

None.

Product Affected:

F280033SPM	F280037CSPM	F280037SPMR.B	F280039CSPZ.B
F280033SPM.A	F280037CSPM.A	F280037SPZ	F280039CSPZR
F280033SPM.B	F280037CSPM.B	F280037SPZ.A	F280039CSPZR.A
F280033SPZ	F280037CSPMR	F280037SPZ.B	F280039CSPZR.B
F280033SPZ.A	F280037CSPZ	F280039CSPM	F280039SPM
F280033SPZ.B	F280037CSPZ.A	F280039CSPM.A	F280039SPM.A
F280034SPM	F280037CSPZ.B	F280039CSPM.B	F280039SPM.B
F280034SPM.A	F280037SPM	F280039CSPMR	F280039SPZ
F280034SPM.B	F280037SPM.A	F280039CSPMR.A	F280039SPZ.A
F280034SPZ	F280037SPM.B	F280039CSPMR.B	F280039SPZ.B
F280034SPZ.A	F280037SPMR	F280039CSPZ	
F280034SPZ.B	F280037SPMR.A	F280039CSPZ.A	

Qualification Report

Approve Date 19-NOVEMBER -2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: F280039CSPM	Qual Device: F280039CSPZ	Qual Device: F280037CSPT
		Assembly MQ	Per AT Specification	-	1 lot : Passed	1 lot : Passed	1 lot : Passed

QBS: Qual By Similarity, also known as Generic Data
Qual Device F280039CSPM is qualified at MSL3 260C
Qual Device F280039CSPZ is qualified at MSL3 260C
Qual Device F280037CSPT is qualified at MSL3 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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